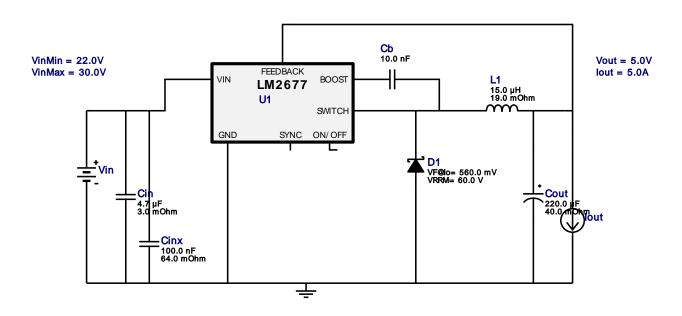


# WEBENCH® Design Report

Design: 4270138/2 LM2677SX-5.0/NOPB LM2677SX-5.0/NOPB 22.0V-30.0V to 5.00V @ 5.0A

 $\begin{aligned} & \text{VinMin} = 22.0 \text{V} \\ & \text{VinMax} = 30.0 \text{V} \\ & \text{Vout} = 5.0 \text{V} \\ & \text{lout} = 5.0 \text{A} \end{aligned}$ 

Device = LM2677SX-5.0/NOPB Topology = Buck Created = 2/4/15 4:50:43 AM BOM Cost = \$4.55 Footprint = 536.0 mm<sup>2</sup> BOM Count = 7 Total Pd = 4.0W

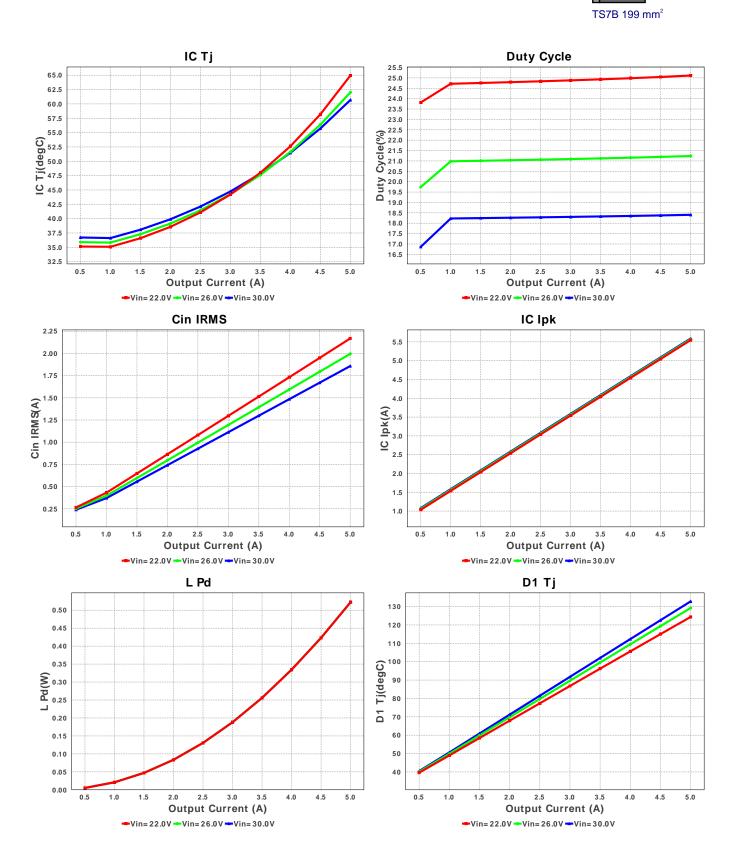


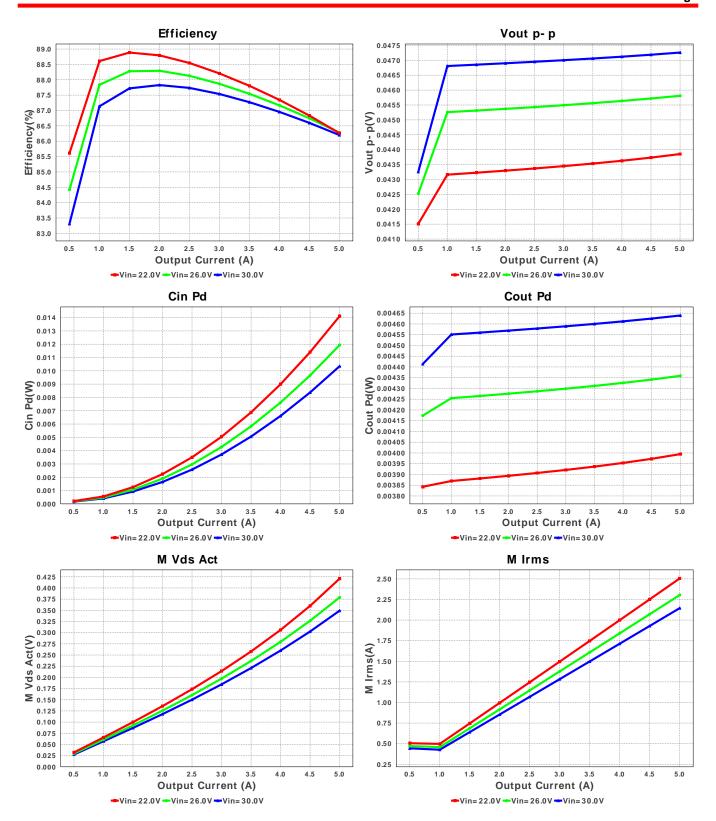
#### **Electrical BOM**

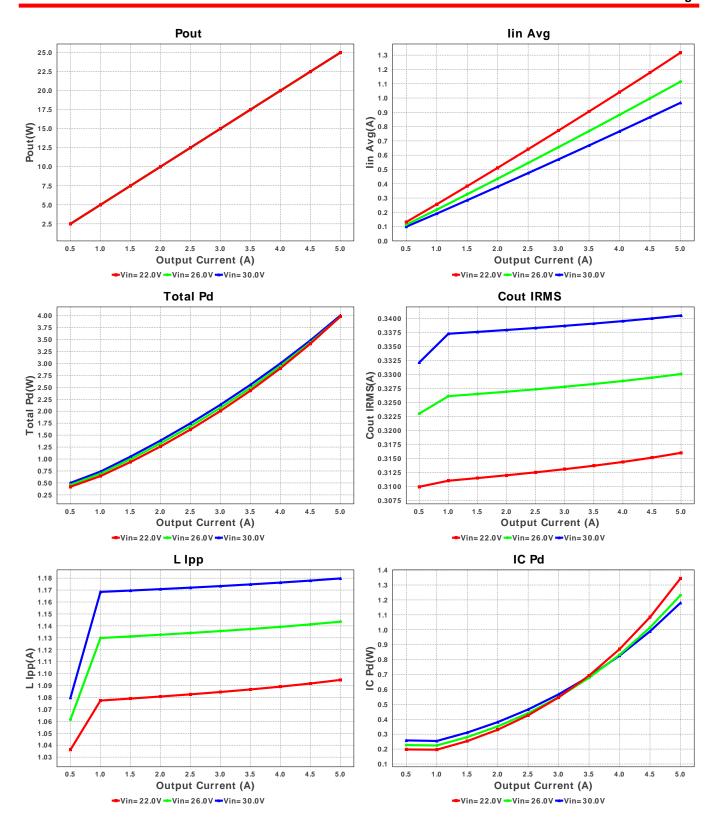
#	Name	Manufacturer	Part Number	Properties	Qty	Price	Footprint
1.	Cb	MuRata	GRM216R71H103KA01D Series= X7R	Cap= 10.0 nF VDC= 50.0 V IRMS= 0.0 A	1	\$0.01	0805 7 mm <sup>2</sup>
2.	Cin	MuRata	GRM31CR71H475KA12L Series= X7R	Cap= 4.7 uF ESR= 3.0 mOhm VDC= 50.0 V IRMS= 4.98 A	1	\$0.22	1206 11 mm <sup>2</sup>
3.	Cinx	Kemet	C0805C104K5RACTU Series= X7R	Cap= 100.0 nF ESR= 64.0 mOhm VDC= 50.0 V IRMS= 1.64 A	1	\$0.01	0805 7 mm <sup>2</sup>
1.	Cout	Panasonic	10TPB220ML Series= ?	Cap= 220.0 uF ESR= 40.0 mOhm VDC= 10.0 V IRMS= 2.0 A	1	\$0.65	7343-31 59 mm²
5.	D1	Diodes Inc.	PDS760-13	VF@Io= 560.0 mV VRRM= 60.0 V	1	\$0.60	PowerDI5 50 mm <sup>2</sup>
3.	L1	Coilcraft	MSS1210-153MEB	L= 15.0 μH DCR= 19.0 mOhm	1	\$0.81	

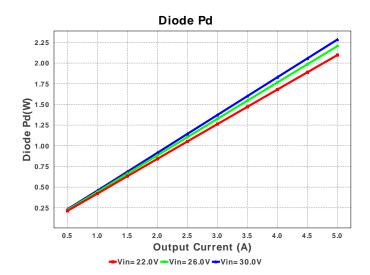
MSS1210 204 mm<sup>2</sup>

#	Name	Manufacturer	Part Number	Properties	Qty	Price	Footprint
7.	U1	Texas Instruments	LM2677SX-5.0/NOPB	Switcher	1	\$2.25	









### **Operating Values**

Operating values							
#	Name	Value	Category	Description			
1.	Cin IRMS	1.857 A	Current	Input capacitor RMS ripple current			
2.	Cout IRMS	340.563 mA	Current	Output capacitor RMS ripple current			
3.	IC lpk	5.59 A	Current	Peak switch current in IC			
4.	lin Avg	966.74 mA	Current	Average input current			
5.	L lpp	1.18 A	Current	Peak-to-peak inductor ripple current			
6.	M1 Irms	2.145 A	Current	Q lavg			
7.	BOM Count	7	General	Total Design BOM count			
8.	FootPrint	536.0 mm <sup>2</sup>	General	Total Foot Print Area of BOM components			
9.	Frequency	260.0 kHz	General	Switching frequency			
10.	IC Tolerance	100.0 mV	General	IC Feedback Tolerance			
11.	M Vds Act	349.245 mV	General	Voltage drop across the MosFET			
12.	Pout	25.0 W	General	Total output power			
13.	Total BOM	\$4.55	General	Total BOM Cost			
14.	D1 Tj	132.811 degC	Op_Point	D1 junction temperature			
15.	Vout OP	5.0 V	Op_Point	Operational Output Voltage			
16.	Cross Freq	50.731 kHz	Op_point	Bode plot crossover frequency			
17.	Duty Cycle	18.404 %	Op_point	Duty cycle			
18.	Efficiency	86.2 %	Op_point	Steady state efficiency			
19.	IC Tj	60.683 degC	Op_point	IC junction temperature			
20.	ICThetaJA	26.0 degC/W	Op_point	IC junction-to-ambient thermal resistance			
21.	IOUT_OP	5.0 A	Op_point	lout operating point			
22.	Phase Marg	94.459 deg	Op_point	Bode Plot Phase Margin			
23.	VIN_OP	30.0 V	Op_point	Vin operating point			
24.	Vout p-p	47.26 mV	Op_point	Peak-to-peak output ripple voltage			
25.	Cin Pd	10.348 mW	Power	Input capacitor power dissipation			
26.	Cout Pd	4.639 mW	Power	Output capacitor power dissipation			
27.	Diode Pd	2.285 W	Power	Diode power dissipation			
28.	IC Pd	1.18 W	Power	IC power dissipation			
29.	L Pd	522.5 mW	Power	Inductor power dissipation			
30.	Total Pd	4.002 W	Power	Total Power Dissipation			

### **Design Inputs**

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#	Name	Value	Description			
1.	lout	5.0	Maximum Output Current			
2.	lout1	5.0	Output Current #1			
3.	VinMax	30.0	Maximum input voltage			
4.	VinMin	22.0	Minimum input voltage			
5.	Vout	5.0	Output Voltage			
6.	Vout1	5.0	Output Voltage #1			
7.	base_pn	LM2677	Base Product Number			
8.	source	DC	Input Source Type			
9.	Та	30.0	Ambient temperature			

## Design Assistance

1. LM2677 Product Folder: http://www.ti.com/product/lm2677: contains the data sheet and other resources.

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